

Soldering & Desoldering

Liquid Flux + Thinners

Detailed product specifications are available on: us.100y.com.tw



Product Description

Kester 186, under MIL-F-14256, was QPL approved as Type RMA. Although the fluxing ability approaches that of Type RAflux, the flux residue after soldering is non-corrosive and non-conductive. Kester 186 rosin flux has been developed for use in critical applications where difficult assemblies are to be soldered, but process requirements stipulate use of Type RMAflux. This flux possess high thermal stability for soldering multi-layer assemblies which require a high preheat temperature. Exposure to high preheat temperatures does not degrade solubility of the residue in normal cleaning solvents. There is no surface insulation resistance degradation caused by the flux residue. The use of a minimum of ionic activating agents and the inactive nature of the residue permits leaving the residue on circuit board assemblies for many applications. The flux residue is also moisture and fungus resistant.

Performance Characteristics:

- High thermal stability
- Improves soldering performance
- Eliminates the need and expense of cleaning
- Classified as ROL0 per J-STD-004

Part No.	Product No.	Manufacturer	Description
8090	Flux Pen#186	Kester	Kester_186 Rosin Flux Pen, Type RMA



Performance Characteristics:

- Improves soldering performance
- Classified as ORL0 per J-STD-004
- Eliminates the need and expense of cleaning
- Compliant to Bellcore GR-78
- Non-corrosive tack-free residues

Part No.	Product No.	Manufacturer	Description	Weight	Boiling
8085	Flux Pen#951	Kester	Kester_Low Low Solid, No-Clean Flux Pen	90g	79°C

Performance Characteristics:

- Improves soldering performance
- Classified as ORL0 per J-STD-004
- Eliminates the need and expense of cleaning
- Compliant to Bellcore GR-78
- Non-corrosive tack-free residues

Part No.	Product No.	Manufacturer	Description	Weight	Boiling
8104	Flux#951E	Kester	Kester_951-E Low Residue Soldering Flux	4L/Barrel	79°C



Part No.	Product No.	Description	Weight
17394	NR691-1 gals	Solder Creams	4L/Barrel
17393	NR691-5GAL	Solder Creams	5gallon/Barrel

APPLICATIONS

- WS600 Red: Standard flux for BGA/CSP applications.
- WS600MHV Red: Modified flux for higher viscosity, stencil printing and higher humidity applications where "hot slump" is a concern.
- WS600L Red: Modified flux for lower viscosity applications.

PHYSICAL AND CHEMICAL PROPERTIES

Color	Deep Amber or Deep Red
Tack Strength (g/cc)	~ 15
Stencil Life, 40-60%RH/20-25°C (hours):	~ 8
Water Extract Resistivity (ohm*cm)	>100,000
Corrosiveness:	Passes Copper Mirror
Halide Content:	Halide Free
pH, Flux Residues	6.8 typical
SIR (ohms) 7 Days	>10 ⁹ , cleaned, 85°C/85% RH (pass >10 ⁷)
Wetting Balance	Faster than traditional RMA's
Carrier Resin	Completely Water Soluble

Part No.	Product No.	Manufacturer	Description	Weight
22580	WS600	COOKSON	BGA Flux	150 GRAMS



Part No.	Product No.	Description	Weight
40320	YC-625A-2	Solder Creams	2kg
5936	YC-625A250ML	Solder Creams	250g
3229	YC-625B	Solder Creams	250g
40386	YC-625B-2	Solder Creams	2kg
3230	YC-625C	Solder Creams	250g
40385	YC-625C-2	Solder Creams	2kg



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